# ΔΙΑΛΕΞΗ

Στις 7 Σεπτεμβρίου 2016, ημέρα Τετάρτη και ώρα 15.30 ο καθηγητής του πολυτεχνείου του Βουκουρεστίου **Dr. Norocel Dragoş Codreanu** θα δώσει διάλεξη με τίτλο:

## "Advanced design and virtual investigations of PCB structures and electronic modules"

Η διάλεξη θα πραγματοποιηθεί στην αίθουσα Γενικών Συνελεύσεων του Τμήματος Φυσικής (4ος όροφος - μικρό ασανσέρ ανατολικά)

### Presentation overview

The presentation provides to participants an overview of high performance PCB design and virtual investigations of PCB structures & electronic modules for high-speed/high-frequency/high-density applications and presents, based on numerous figures, formulas, case studies and examples, a practical approach on development, evaluation, and manufacturing of on-board interconnection structures. It will cover a large area of topics, from fundamentals of PCB design to signal integrity issues, full-wave electromagnetic modeling and simulation, investigation techniques and CAE-CAD tools. The lecturer will provide also a few useful software tools and links to various other software tools necessary for advanced investigation/evaluation of PCB structures and PCB based modules and systems.

### *CV*

**Norocel-Dragoş Codreanu,** Ph.D., is full professor at "Politehnica" University of Bucharest (UPB), Romania, Faculty of Electronics, Telecommunications and Information Technology, Department of Electronics Technology and Reliability (TEF), being currently the executive manager of the UPB university research centre "Center for Technological Electronics and Interconnection Techniques" (UPB-CETTI). He has received his formal education at UPB, obtaining his M.S. in radio-communications in 1988. He has joined UPB in 1992, where he has received the Ph.D. degree in 1999, after a research period at Budapest University of Technology & Economics, Hungary. He is specialist in electronic packaging and advanced technologies, being focused on CAE-CAD-CAM for electronic modules/assemblies development, high-speed/high-frequency PCB/MCM-L design and manufacturing, full-wave electromagnetic modeling and simulation of planar structures, printed circuit/wiring board fabrication processes, electronic assembling technologies and heterogeneous integration (including Lead-Free issues, fine-pitch/high-density interconnections, package-on-package, system-in-package, thermal management, a.s.o. Additionally, he has expertise in IR thermovision/thermography for electrical/electronic systems and in standardization for the electronics industry. He has been senior researcher or manager for more than 25 national and international projects focused on innovation, technology transfer, education and partnerships with industry. He has authored more than 150 scientific contributions/reports/articles and papers (author or co-author) and 7 text books (author or co-author) in electronic packaging and related fields.